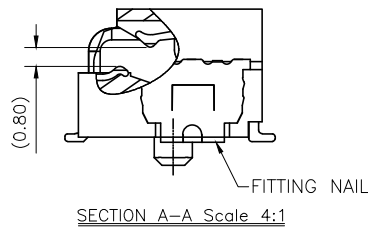
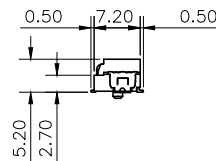
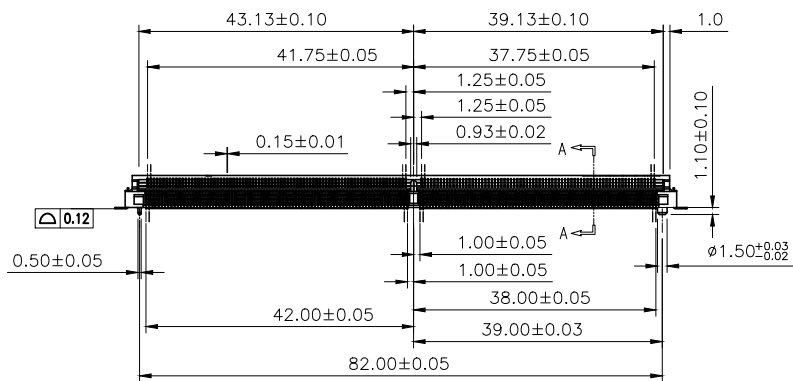
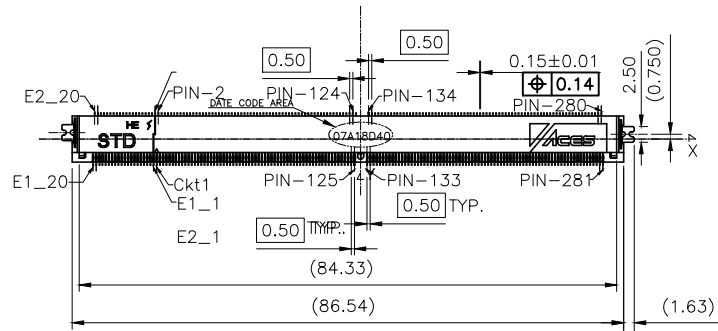




A B C D E F



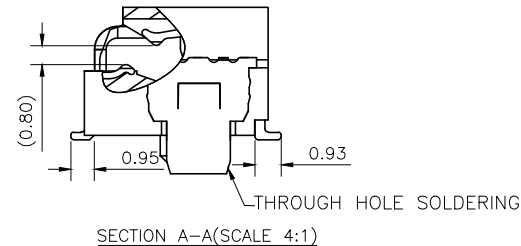
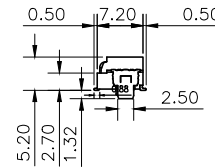
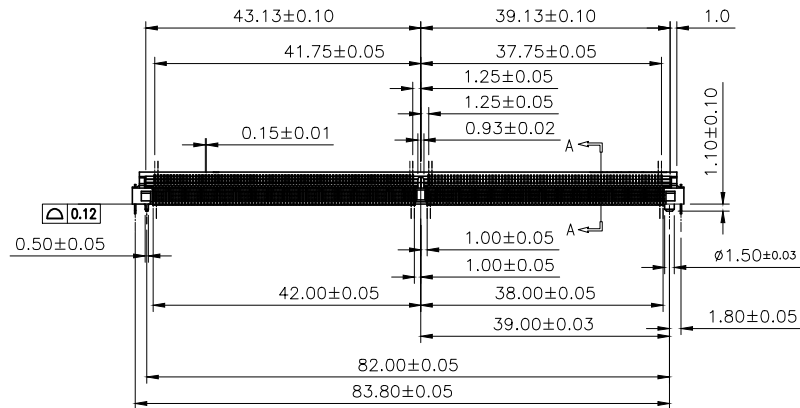
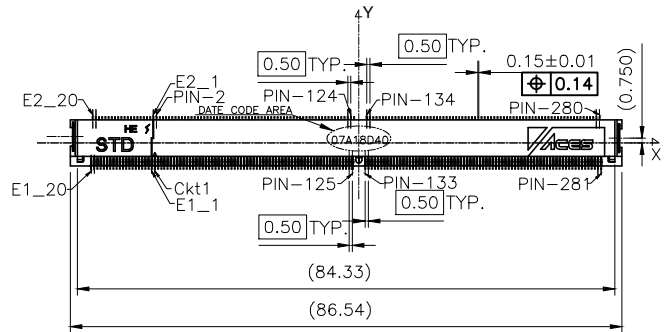
- NOTES:
- MATERIAL:
    - HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR: BLACK.
    - CONTACT: COPPER ALLOY
    - FITTING NAIL: COPPER ALLOY
    - BOARD LOCK: COPPER ALLOY
  - FINISH:
    - CONTACT:
      - UNDERPLATING: 50u" MIN. NICKEL OVERALL.
      - 8: GOLD 3u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
      - M: GOLD 3u" ON CONTACT AREA AND SOLDER TAIL
      - T: GOLD 10u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
      - C: GOLD 15u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA
      - D: GOLD 30u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA
    - FITTING NAIL:
      - UNDERPLATING: 50u" MIN. NICKEL OVERALL.
      - FINISH: 100~200u" MATT TIN OVER ALL
  - REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
  - ROHS COMPLIANT PRODUCT.
  - SPEC. PLS. REFER TO PS-91781-xxxx
  - PACKING SPEC. PLS. REFER TO 91781-314xx(TRAY)
  - PACKING SPEC. PLS. REFER TO 91781-314xx(REEL)
  - SUGGESTION: PLS PAY ATTN TO THE DEFORMATION DIRECTION OF PCB-SMT IN CONNECTOR LAYOUT AREA
  - THE PCB WARPAGE : 0.05MAX.
  - THE PCB Coplanarity : 0.08MAX.(ex.86.54mm&CONN.LAYOUT AREA).
  - PART NUMBER

91781-XXX X X-XXX	
NO OF CKT 314: 314 PIN	XXX PIN POLARIZATION 001 S.M. (SEE SHEET-1) 002 THROUGH HOLE (SEE SHEET-2)
PACKING 0: REEL 2: TRAY U: REEL (PLASTIC)	PLATING 8: GOLD 3u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL M: GOLD 3u" MIN ON CONTACT AREA AND SOLDER TAIL T: GOLD 10u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL C: GOLD 15u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA D: GOLD 30u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA

QUALITY SYMBOLS MAJOR CRITICAL GENERAL TOLERANCES (UNLESS SPECIFIED) X ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY Zhang, hongjun	DATE 19/01/23	
	CHECKED BY Lu, Jing Quan	DATE 19/01/23	
	APPROVED BY hsieh, fu yu	DATE 19/01/23	SIZE A4
	UNITS mm		DWG NO. 91781-314XX-XXX
	SCALE 2:1	SHEET NO. 1 OF 5	REV E
			PART NO. SEE NOTES

B C D E F

1  
2  
3  
4  
5



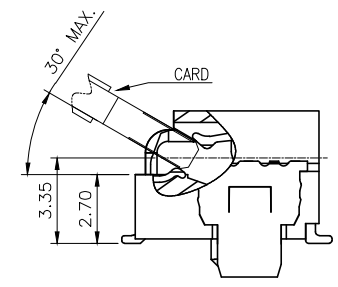
NOTES:

1. MATERIAL:
  - 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR: BLACK.
  - 1.2 CONTACT: COPPER ALLOY
  - 1.3 FITTING NAIL: COPPER ALLOY
  - 1.4 BOARD LOCK: COPPER ALLOY
2. FINISH:
  - 2.1 CONTACT:
    - UNDERPLATING: 50u" MIN. NICKEL OVERALL.
    - 8: GOLD 3u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
    - M: GOLD 3u" ON CONTACT AREA AND SOLDER TAIL
    - T: GOLD 10u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
    - C: GOLD 15u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA
    - D: GOLD 30u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA
  - 2.2 FITTING NAIL:
    - UNDERPLATING: 50u" MIN. NICKEL OVERALL.
    - FINISH:100~200u" MATT TIN OVER ALL
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
4. ROHS COMPLIANT PRODUCT.
5. SPEC. PLS. REFER TO PS-91781-xxxx
6. PACKING. SPEC. PLS. REFER TO 91781-314xx(TRAY)
7. PACKING SPEC. PLS. REFER TO 91781-314xx(REEL)
8. SUGGESTION: PLS PAY ATTN TO THE DEFORMATION DIRECTION OF PCB-SMT IN CONNECTOR LAYOUT AREA
9. THE PCB WARPAGE : 0.05MAX.
10. THE PCB Coplanarity : 0.08MAX.(ex.86.54mm&CONN.LAYOUT AREA).
11. PART NUMBER

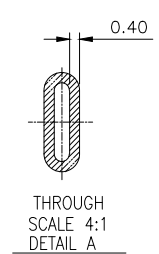
91781-XXX X X-XXX		
NO OF CKT	X	X-XXX
314: 314 PIN	XXX	FIN POLARIZATION
	00	SMT (SEE SHEET-1)
PACKING	000	THROUGH HOLE (SEE SHEET-2)
0:REEL		
2:TRAY		
U:REEL(PLASTIC)		
		PLATING

- 8: GOLD 3u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
- M: GOLD 3u" MIN ON CONTACT AREA AND SOLDER TAIL
- T: GOLD 10u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
- C: GOLD 15u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA
- D: GOLD 30u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA

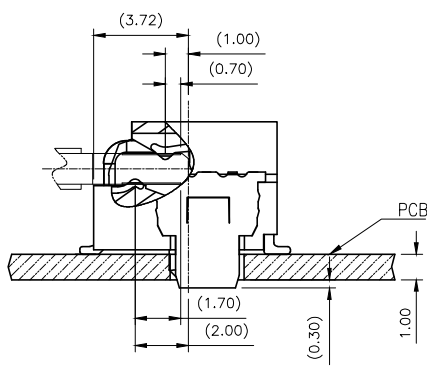
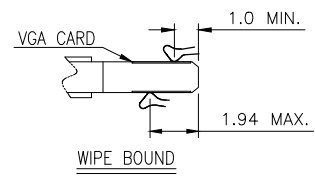
QUALITY SYMBOLS	DRAWN BY	DATE				
MAJOR	Zhang,hongjun	19/01/23				
CRITICAL	CHECKED BY	DATE	TITLE MXM-3 314 PINS 0.5mm PITCH EDGE CARD CONN. SMT D/R R/A STD TYPE H=5.2mm (BTB H=2.7)			
GENERAL TOLERANCES (UNLESS SPECIFIED)	Lu, Jing Quan	19/01/23				
X. ±0.5	APPROVED BY	DATE	UNITS	SIZE	DWG NO.	
.X ±0.25	hsieh, fu yu	19/01/23	mm		A4	91781-314XX-XXX
.XX ±0.15			SCALE	SHEET NO.	REV	PART NO.
.XXX ±0.1			2 : 1	2 OF 5	E	SEE NOTES
ANGLES ±2°						



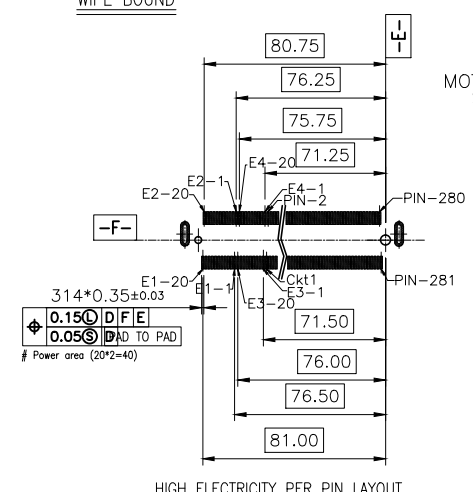
PCB 30° MAX In conn. Scale 4:1



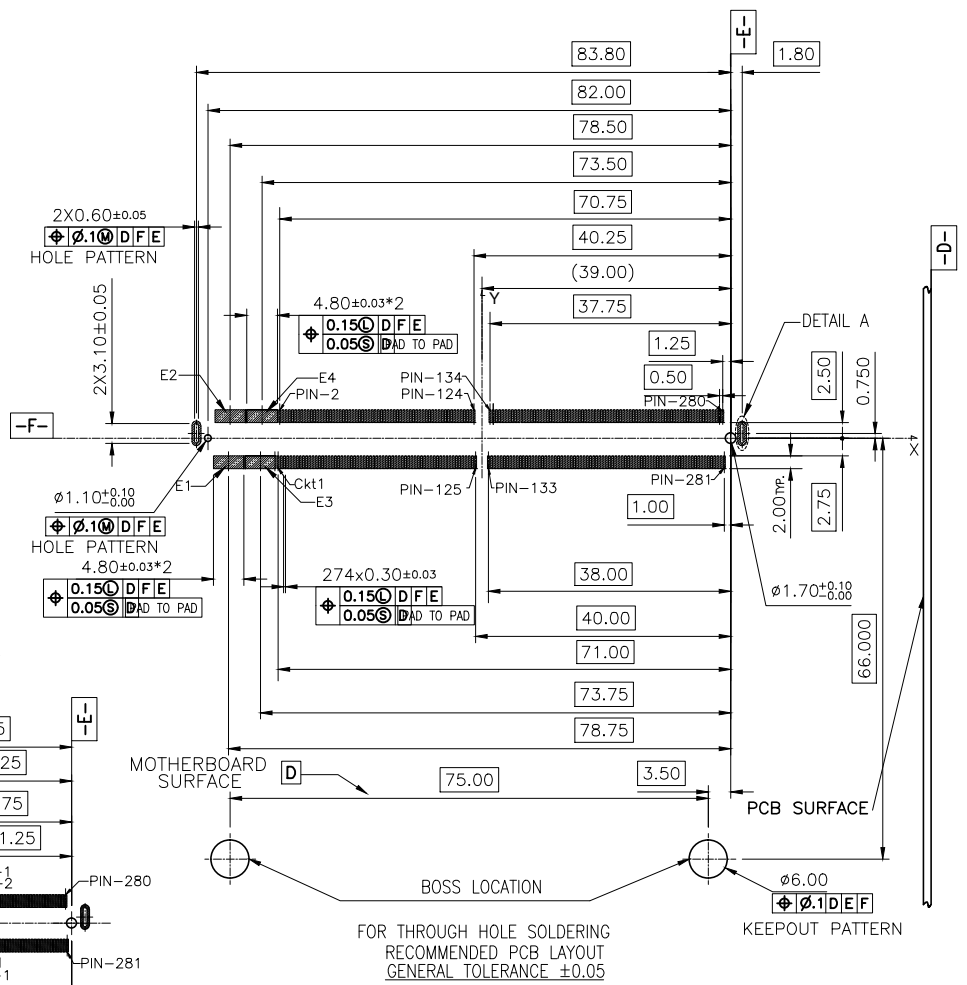
THROUGH HOLE SCALE 4:1 DETAIL A



PCB on 90° Scale 4:1

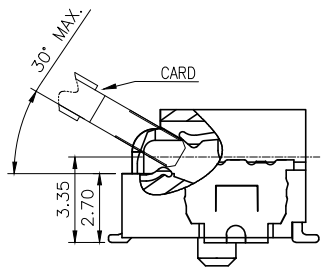


HIGH ELECTRICITY PER PIN LAYOUT

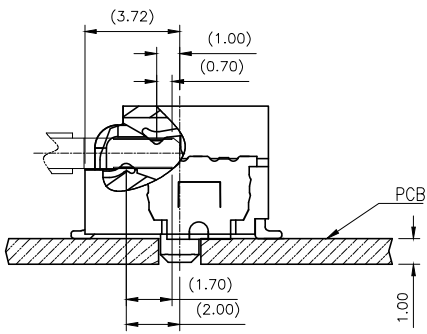
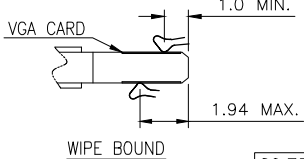


FOR THROUGH HOLE SOLDERING  
RECOMMENDED PCB LAYOUT  
GENERAL TOLERANCE ±0.05

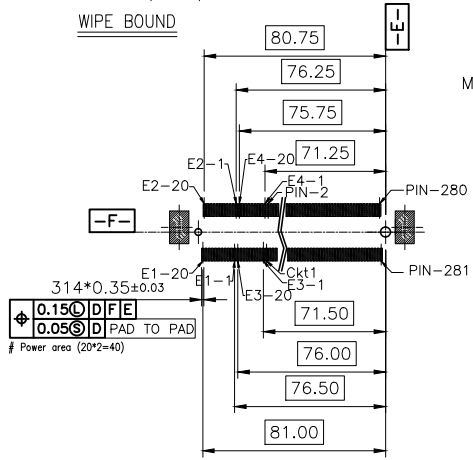
<b>QUALITY SYMBOLS</b> MAJOR CRITICAL <b>GENERAL TOLERANCES (UNLESS SPECIFIED)</b> X ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY Zhang, hongjun	DATE 19/01/23	
	CHECKED BY Lu, Jing Quan	DATE 19/01/23	
	APPROVED BY hsieh, fu yu	DATE 19/01/23	UNITS mm
	SCALE 2:1	SHEET NO. 3 OF 5	SIZE A4
			DWG NO. 91781-314XX-XXX
			PART NO. SEE NOTES



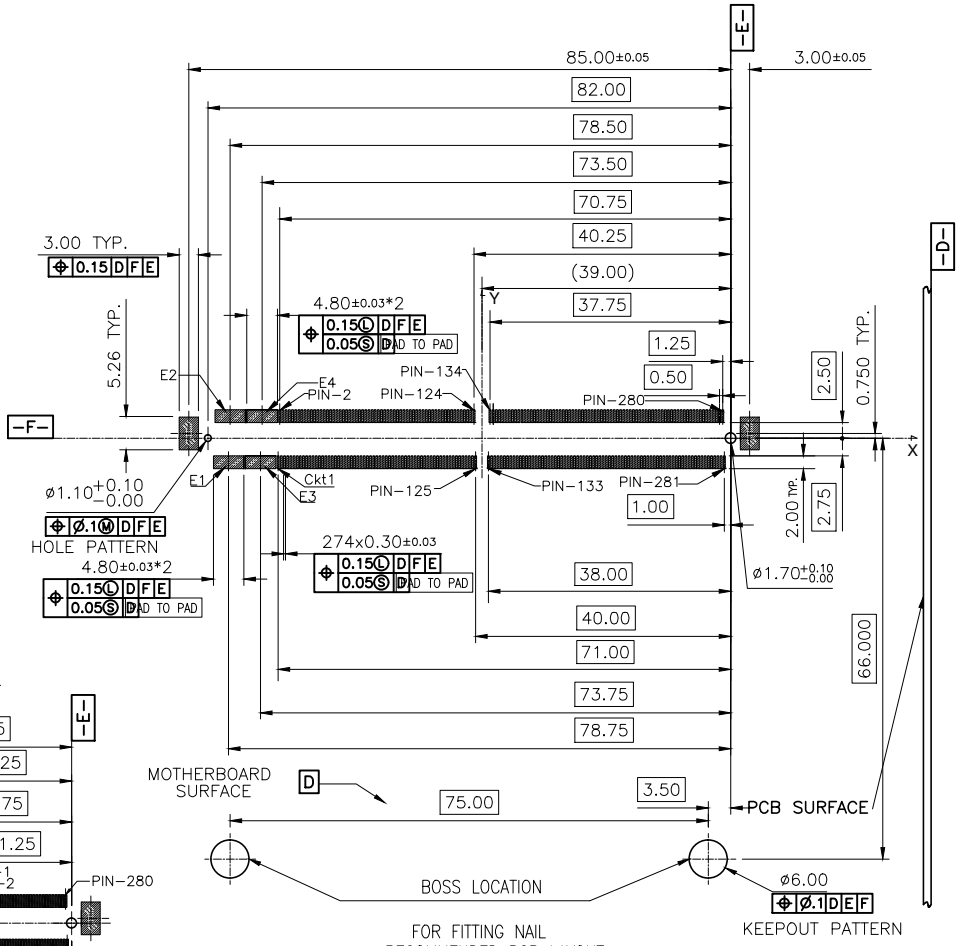
PCB 30° MAX In conn. Scale 4:1



PCB on 90° Scale 4:1



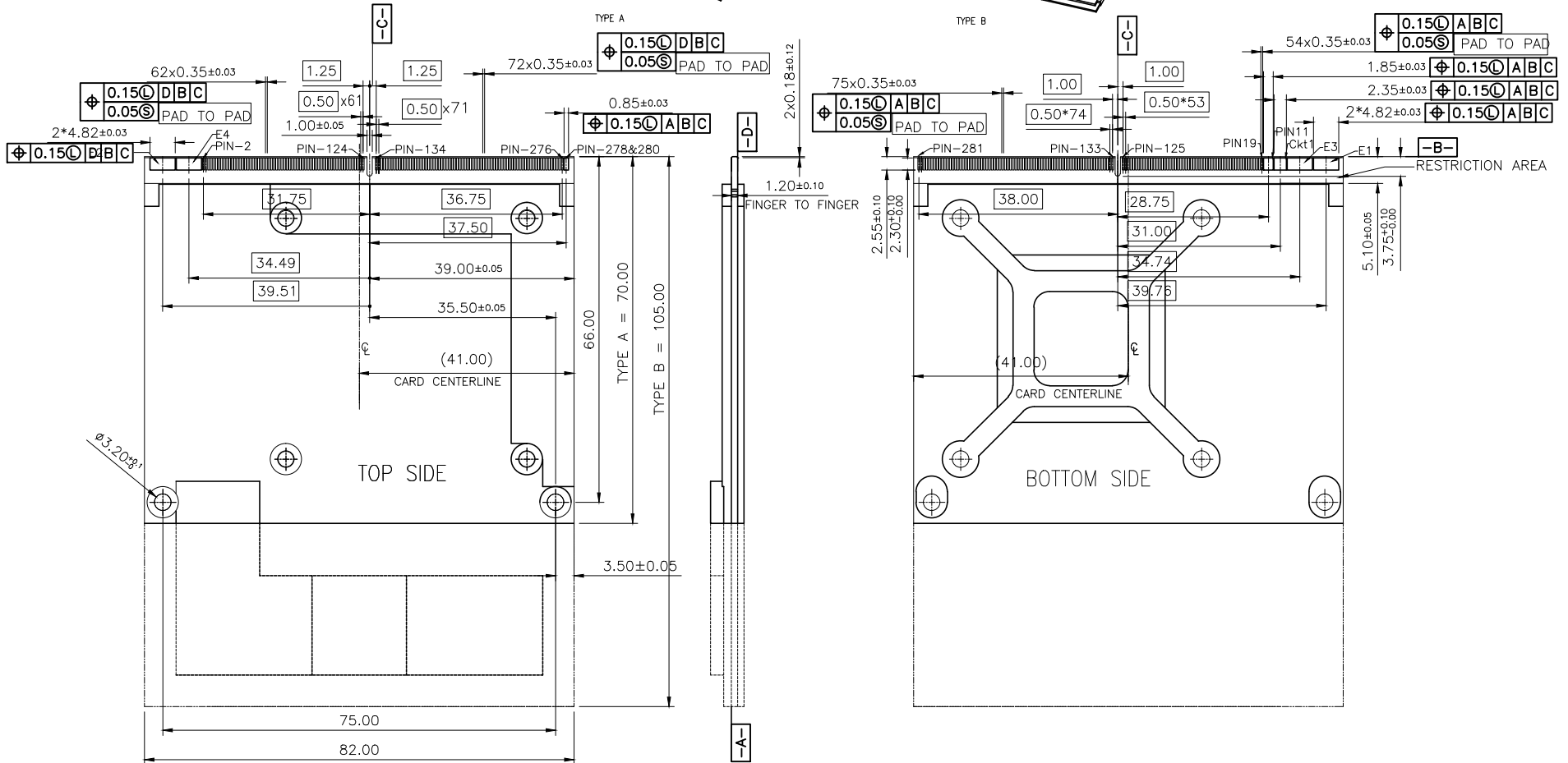
HIGH ELECTRICITY PER PIN LAYOUT



FOR FITTING NAIL  
RECOMMENDED PCB LAYOUT  
GENERAL TOLERANCE ±0.05

KEEPOUT PATTERN

<b>QUALITY SYMBOLS</b> MAJOR Ⓢ CRITICAL Ⓢ	DRAWN BY	DATE	
	Zhang,hongjun	19/01/23	
<b>GENERAL TOLERANCES (UNLESS SPECIFIED)</b> X ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	CHECKED BY	DATE	<b>TITLE</b> MXM-3 314 PINS 0.5mm PITCH EDGE CARD CONN. SMT D/R R/A STD TYPE H=5.2mm (BTB H=2.7)
	Lu, Jing Quan	19/01/23	
	APPROVED BY	DATE	UNITS mm
	hsieh, fu yu	19/01/23	
	SCALE	SHEET NO.	SIZE
	2 : 1	4 OF 5	A4
			DWG NO.
			91781-314XX-XXX
			PART NO.
			SEE NOTES



MXM-3 314PIN GOLD FINGER

MXM-3 MAX 321 CONTACT LOCATION  
314 USEABLE (7 LOST TO KEY)

<b>QUALITY SYMBOLS</b> MAJOR $\pm 0.5$ CRITICAL $\pm 0.15$	DRAWN BY Zhang, hongjun DATE 19/01/23	
	CHECKED BY Lu, Jing Quan DATE 19/01/23	
<b>GENERAL TOLERANCES</b> (UNLESS SPECIFIED) X $\pm 0.5$ .X $\pm 0.25$ .XX $\pm 0.15$ .XXX $\pm 0.1$ ANGLES $\pm 2^\circ$	APPROVED BY hsieh, fu yu DATE 19/01/23	<b>STANDARD</b> SMT D/R R/A STD TYPE H=5.2mm (BTB H=2.7)
	UNITS mm	
SCALE 2:1	SHEET NO. 5 OF 5	<b>DWG NO.</b> 91781-314XX-XXX
	<b>REV</b> E	<b>PART NO.</b> SEE NOTES